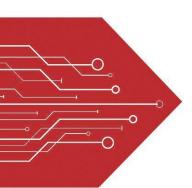
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data speet

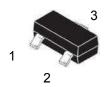


Semiconductor

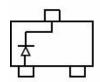
Compiance

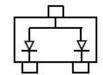
FEATURES

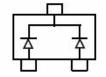
Extremely Fast Switching Speed

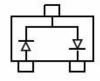


SOT-23









BAT54 MARKING: KL1

BAT54A MARKING: KL2

BAT54C MARKING: KL3

BAT54S MARKING: KL4

Maximum Ratings @T_A=25℃

Parameter	Symbol	Limits	Unit
Peak Repetitive Peak reverse voltage	V_{RRM}		
Working Peak Reverse Voltage	V _{RWM}	30	V
	V _R	200	
Forward Continuous Current	I _{FM}	200	mA mA
Power Dissipation	P _D	200	mW
Storage temperature	T _{STG}	-55-150	°C

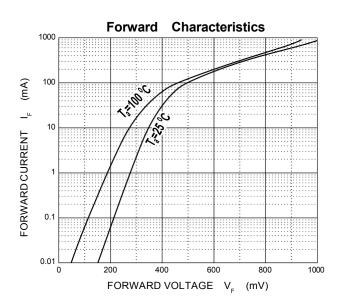
Electrical Characteristics @T_A=25°C

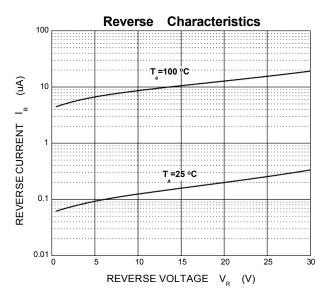
Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Reverse Breakdown Voltage	V (BR)R	30			V	IR=100µA
	V _{F1}			0.24	V	I _F =0.1mA
	V _{F2}			0.32	V	I _F =1mA
Forward voltage	V _{F3}			0.40	V	I⊧=10mA
	V _{F4}			0.50	V	I _F =30mA
	V _{F5}			1	V	I _F =100mA
Reverse current	I _R			2	μΑ	V _R =25V
Diode Capacitance	C _D			10	pF	V _R =1V,f=1MHz
				_		I _F =I _R =10mA
Reverse Recovery Time	t _{rr}			5	nS	Irr=0.1 XI_R , R_L =100 Ω

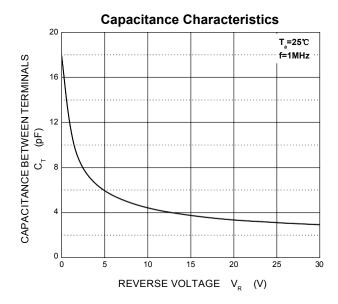


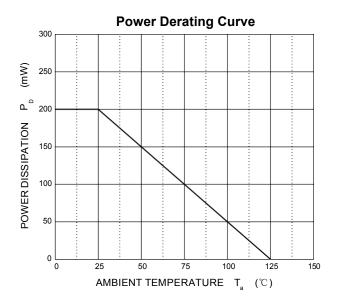


Typical Characteristics



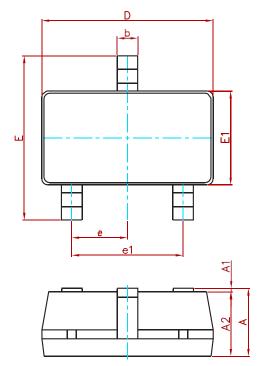


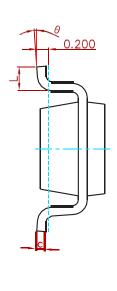






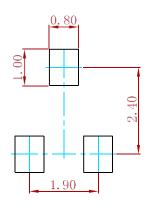
PACKAGE MECHANICAL DATA





Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
Syllibol	Min.	Max.	Min.	Max.	
Α	1.050	1.250	0.041	0.049	
A1	0.000	0.100	0.000	0.004	
A2	1.050	1.150	0.041	0.045	
b	0.300	0.500	0.012	0.020	
С	0.100	0.200	0.004	0.008	
D	2.820	3.020	0.111	0.119	
E1	1.500	1.700	0.059	0.067	
Е	2.650	2.950	0.104	0.116	
е	0.950(BSC)	0.037	(BSC)	
e1	1.800	2.000	0.071	0.079	
L	0.300	0.600	0.012	0.024	
0	0°	8°	0°	8°	

Suggested Pad Layout



- 1.Controlling dimension:in millimeters.
 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAT54/A/C/S	SOT-23	3000



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